



TDG HOLDING CO., LTD.

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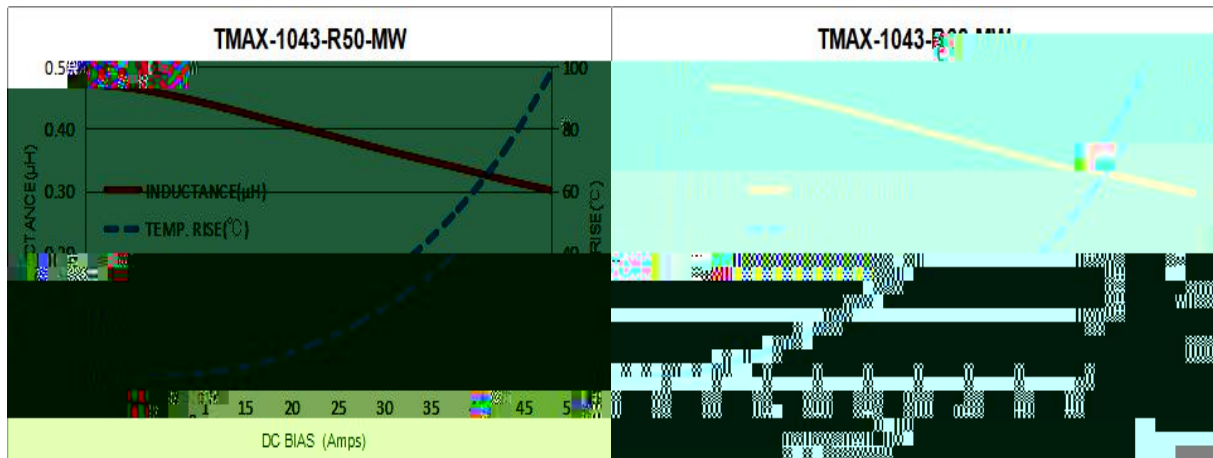
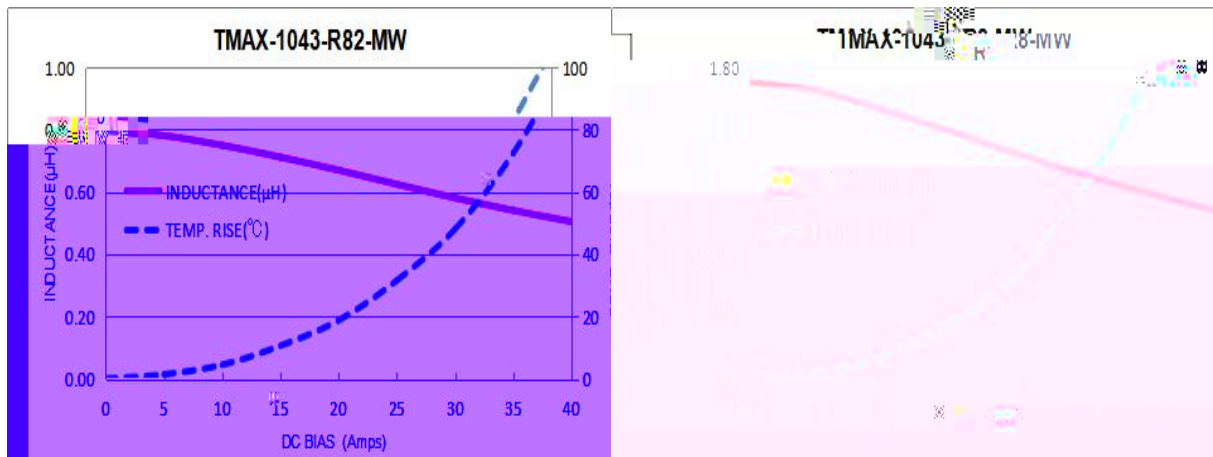




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Inductance and Temperature Rise vs. DC Current





Reliability:

Item	Test Method	Specification and Requirement



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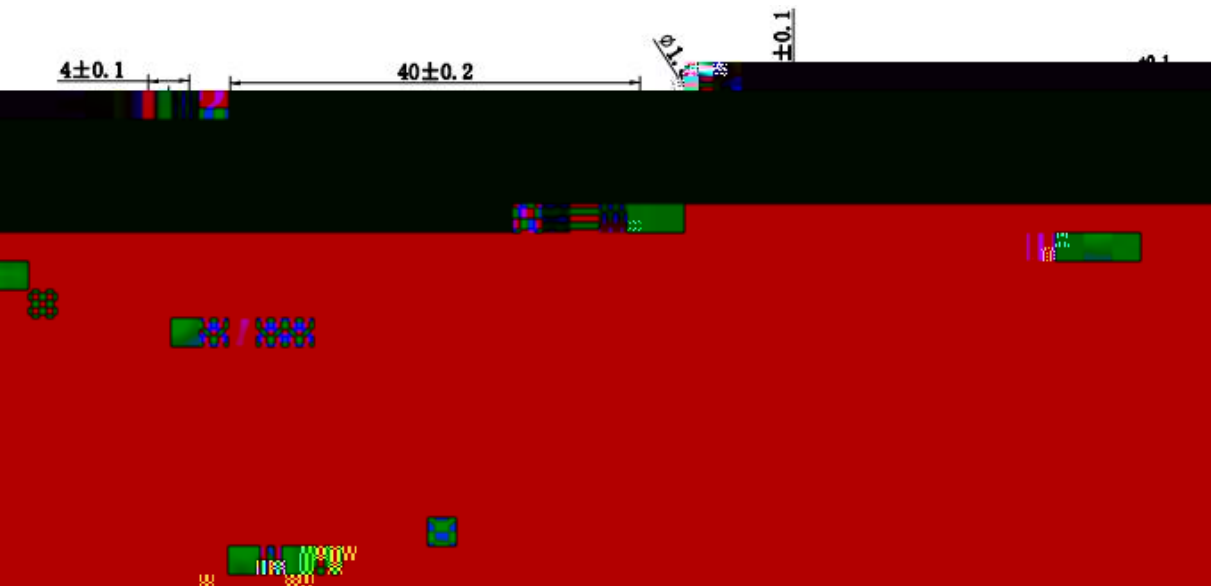
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Reliability:

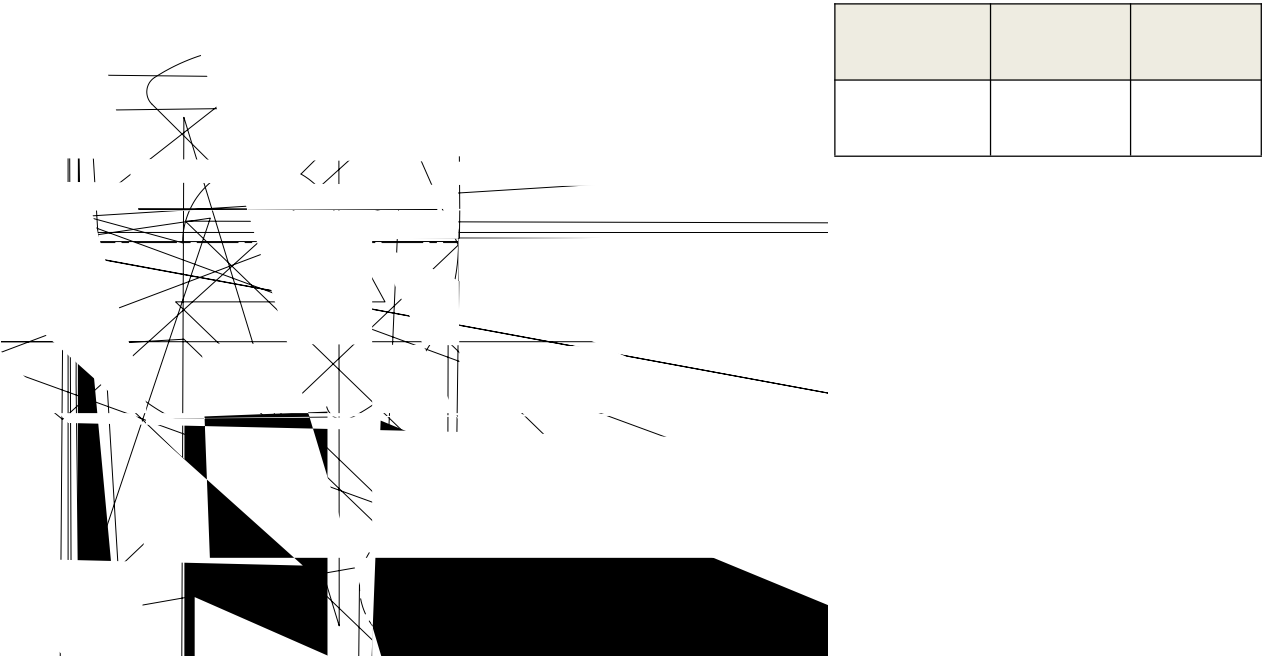
Item	Test Method	Specification and Requirement
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Packaging Dimensions



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Reflow Profile

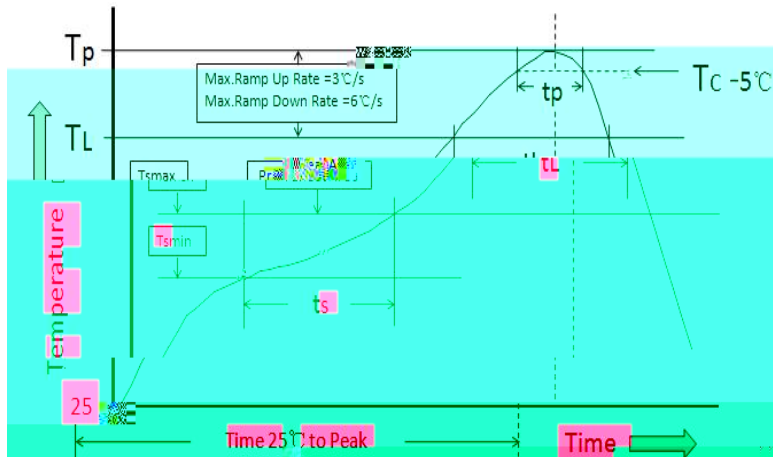


Table1-StandardSnPb Solder(Tc)

Package Thickness	Volume mm ³ 350	Volume mm ³ 350

Table2-Lead(Pb)Free Solder(Tc)

Package Thickness	Volume mm ³ 350	Volume mm ³ 350-2000	Volume mm ³ >2000

Reference JDEC J-STD-020(latest revision)

Profile Feature

Standard SnPb solder

Lead(Pb) Free Solder

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